This presentation has been prepared by Samsung Electronics Co., Ltd. (the "Company"). It does not purport to contain all the information that a prospective investor may require in connection with any potential investment in the Company. You should not treat the contents of this presentation, or any information provided in connection with it, as financial advice, financial product advice or advice relating to legal, taxation or investment matters.

No representation or warranty (whether express or implied) is made by the Company or any of its officers, advisers, agents or employees as to the accuracy, completeness or reasonableness of the information, statements, opinions or matters (express or implied) arising out of, contained in or derived from this presentation or provided in connection with it, or any omission from this presentation, nor as to the attainability of any estimates, forecasts or projections set out in this presentation.

This presentation is provided expressly on the basis that you will carry out your own independent inquiries into the matters contained in the presentation and make your own independent decisions about the affairs, financial position or prospects of the Company. The Company reserves the right to update, amend or supplement the information at any time in its absolute discretion (without incurring any obligation to do so).

Neither the Company, nor its related bodies corporate, officers, their advisers, agents and employees accept any responsibility or liability to you or to any other person or entity arising out of this presentation including pursuant to the general law (whether for negligence, under statute or otherwise). Any such responsibility or liability is, to the maximum extent permitted by law, expressly disclaimed and excluded. Nothing in this material should be construed as either an offer to sell or a solicitation of an offer to buy or sell securities. It does not include all available information and should not be used in isolation as a basis to invest in the Company.

Future Matters
This presentation contains reference to certain intentions, expectations, future plans, strategy and prospects of the Company. Those intentions, expectations, future plans, strategy and prospects may or may not be achieved. They are based on certain assumptions, which may not be met or on which views may differ and may be affected by known and unknown risks. The performance and operations of the Company may be influenced by a number of factors, many of which are outside the control of the Company. No representation or warranty, express or implied, is made by the Company, or any of its directors, officers, employees, advisers or agents that any intentions, expectations or plans will be achieved either totally or partially or that any particular rate of return will be achieved.

Given the risks and uncertainties may cause the Company's actual future results, performance or achievements to be materially different from those expected, planned or intended, recipients should not place undue reliance on these intentions, expectations, future plans, strategy and prospects. The Company does not warrant or represent that the actual results, performance or achievements will be as expected, planned or intended.

US Disclosure
This document does not constitute any part of any offer to sell, or the solicitation of any offer to buy, any securities in the United States or to, or for the account or benefit of any "US person" as defined in Regulation S under the US Securities Act of 1993 ("Securities Act"). The Company's shares have not been, and will not be, registered under the Securities Act or the securities laws of any state or other jurisdiction of the United States, and may not be offered or sold in the United States or to any US person without being so registered or pursuant to an exemption from registration including an exemption for qualified institutional buyers.
Contents

BUSINESS UPDATE
MARKET OPPORTUNITIES
SAMSUNG STRATEGY
KEY TAKEAWAYS
Financial Highlights

Continuous revenue growth, exceeded $10 billion since 2018
Business Milestones

- Foundry Business Start
- Foundry 1st HKMG Mass Production
- Foundry 1st FinFET Mass Production
- Industry 1st 10nm Mass Production
- Spin-off into Independent Business Unit
- 7nm EUV Production Start
- Completed V1 Line Construction

Timeline:
- S1-Line Construction: 2005
- S2-Line Ramp up: 2011
- 8-inch Business Start: 2015
- 14LPE: 2016
- S3-Line Ramp up: 2017
- 7nm EUV Production Start: 2018
- Completed V1 Line Construction: 2019
Global Manufacturing Sites

Advanced 300mm Fabs, Matured 200mm Fab, Test/Package Facilities

- **SSES**: Samsung Electronics Suzhou Semiconductor
  - Suzhou, China
- **TSP**: Test and System Package
  - Onyang, Korea
- **Line-6**: 180nm~65nm
- **S1-Line**: 65nm~8nm
- **S3-Line**: 10nm~
- **S4-Line**: 65nm~28nm
- **V1 Line**: 7nm~

* SSES: Samsung Electronics Suzhou Semiconductor
* TSP: Test and System Package
Contents

BUSINESS UPDATE
MARKET OPPORTUNITIES
SAMSUNG STRATEGY
KEY TAKEAWAYS
New applications emerge with 5G, bringing greater demand for semiconductor foundry.

Foundry will be a pathfinder in realizing unforeseen technology.

- **Mobile and Network**
- **Advanced Driver Assistance Systems**
- **High Performance Computing and Artificial Intelligence**

* DSP: Design Solution Partners / EDA: Electronic Design Automation / OSAT: Outsourced Semiconductor Assembly and Test
Foundry Market Opportunities

Foundry Market by Node

Expected to grow more than 5% per year on average by 2022

<table>
<thead>
<tr>
<th>Year</th>
<th>Nodes</th>
</tr>
</thead>
<tbody>
<tr>
<td>'17</td>
<td>130</td>
</tr>
<tr>
<td>'18</td>
<td>90</td>
</tr>
<tr>
<td>'19</td>
<td>65</td>
</tr>
<tr>
<td>'20E</td>
<td>45</td>
</tr>
<tr>
<td>'21E</td>
<td>32/28</td>
</tr>
<tr>
<td>'22E</td>
<td>22/20</td>
</tr>
<tr>
<td>'23E</td>
<td>16/14</td>
</tr>
<tr>
<td>'24E</td>
<td>10</td>
</tr>
<tr>
<td>'25E</td>
<td>7</td>
</tr>
</tbody>
</table>

* Source: Gartner, Samsung Internal

# of Foundry Providers by Node

Now only 2 companies, including Samsung, provide leading-edge foundry services

<table>
<thead>
<tr>
<th>Nodes</th>
<th>Companies</th>
</tr>
</thead>
<tbody>
<tr>
<td>130</td>
<td>22</td>
</tr>
<tr>
<td>90</td>
<td>2</td>
</tr>
<tr>
<td>65</td>
<td>7 &amp; under</td>
</tr>
</tbody>
</table>

* Source: Gartner, Samsung Internal
Our Vision

The Most Trusted Foundry,
providing creative solutions for customers’ innovation needs

Technology
- Unrivaled process technology
- Customer-friendly design infrastructure
- Semiconductor ‘One stop shop’

Operation
- Flawless supply chain management
- Unparalleled execution to deliver our commitment
- Highest level of visibility & flexibility

Service
- Service beyond expectation
- Deep knowledge and expertise to solve customer challenges
- Agile collaboration for customers’ success
Advanced Technology

Maintain firm technology leadership through continuous node scaling

Ready to support a wide variety of applications and customers

Transistor Structure
- Planar
- FinFET
- GAA

Design Rule
- 32/28nm
- 14nm
- 10nm
- 7nm
- 5nm
- 3nm

Lithography Light Source
- ArF
- EUV

Development Schedule
- 2010
- 2012
- 2014
- 2016
- 2018
- 2020

* Gate All Around
Differentiated Platform, FD-SOI

28/18FDS, Solution for IoT, Security, Industrial, and Automotive

- RF : Supports 110GHz mmWave
- eMRAM : Extremely small bitcell, superior write speed and endurance time

<table>
<thead>
<tr>
<th>FDS Technology Offering</th>
<th>Next Generation eMRAM Strategy</th>
</tr>
</thead>
<tbody>
<tr>
<td></td>
<td>28FDS eMRAM solution's Commercial Shipment Started in 2019</td>
</tr>
<tr>
<td></td>
<td>1Gb eMRAM Development on Track</td>
</tr>
<tr>
<td></td>
<td>eMRAM on FinFET Technology under development</td>
</tr>
</tbody>
</table>

<table>
<thead>
<tr>
<th></th>
<th>Logic</th>
<th>RF</th>
<th>eMRAM</th>
</tr>
</thead>
<tbody>
<tr>
<td>28FDS</td>
<td>●</td>
<td>●</td>
<td>●</td>
</tr>
<tr>
<td>18FDS</td>
<td>○</td>
<td>○</td>
<td>○</td>
</tr>
</tbody>
</table>

● Available ○ Under Development
8-inch Value-Added Offerings

Portfolio Expansion from eFlash, Power IC, DDI, CIS, MS/RF to Power-discrete Technologies extensively optimized through many years of product manufacturing
Advanced Package Solutions

Advanced Package Technology Drives System Level Performance Improvement by Enabling More Integration and Better Performance

Mobile Package

- iPoP (integrated Package-on-Package)
- Fan-Out PLP-PoP

HPC Package

- System-on-Film
- 2.5D Si Interposer
- RDL Interposer

*Note: iPoP: integrated Package-on-Package / PLP: Panel-Level-Package / SiP: System-in-Package
'SAFE', the Ecosystem that Samsung Foundry has Built with its Partners, is Always SAFE

- **SAFE**
  - Silicon proven
  - Comprehensive
  - From 350nm↑ to EUV based advanced node
  - For various applications
  - Dedicated and Flexible Technical Support
  - Realize Your Idea
  - Integrated Solutions in Supply Value Chain
  - Effective and Secure
  - Ready to Use Design Environment
  - Everything on the Platform
  - Worldwide Design Service on Cloud

**IP/Library**
- Optimized and Tuned for Samsung’s Foundry Process from RTL to GDS II

**EDA/DM**
- Reference Flow

**Cloud**

---

* IP: Intellectual Property / EDA: Electronic design automation / DM: Design Methodology
Contents

BUSINESS UPDATE
MARKET OPPORTUNITIES
SAMSUNG STRATEGY
KEY TAKEAWAYS
Key Takeaways

- Maintain firm leadership in advanced node technology
- Expanding differentiated offerings and solutions for various applications
- Enhancing state-of-the-art operations to satisfy customers' needs
- Providing best products and services to enable customers' success